TechniFlex LCL1000F/421M U8

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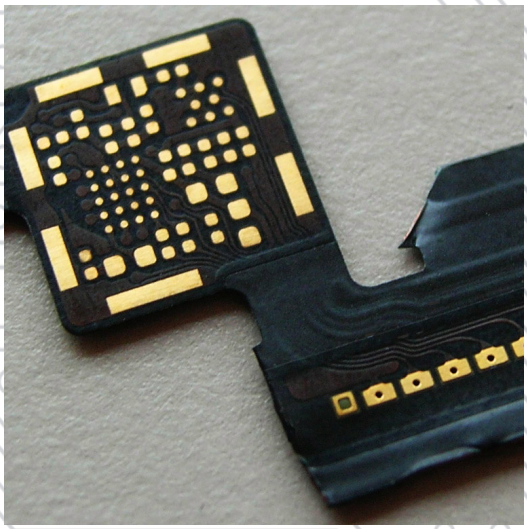
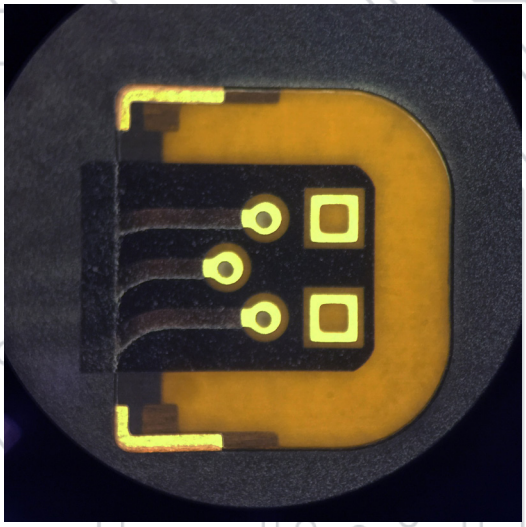
Halogen Free, LED/UV Direct Photoimageable, Black Matte, Flexible Solder Mask

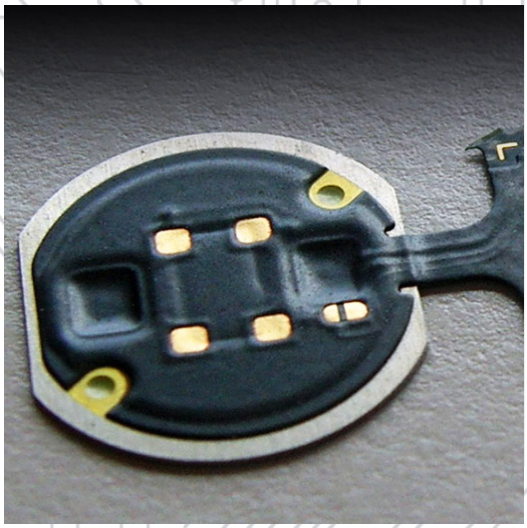


TechniFlex LCL 1000F/421M U8 Direct Imaging is a liquid photo-definable halogen-free flexible black matte solder mask, specially designed for low exposure energy with recently available high output direct imaging systems. It utilizes multiple photoinitiator components and is compatible with standard exposure and UV/LED/Multiple laser direct imaging systems. This DI product exhibits high flexibility and elasticity. It is resistant to multiple soldering operations and is capable of lead-free soldering/hot bar processing.



Features

- Extremely high heat resistance
- Low exposure energy
- Tack free surface after drying
- REACH SVHC Compliant



Benefits

- Withstands multiple soldering operations
- Capable of hot bar processing up to 340°C
- Excellent resistance to ENIG
- Increased productivity with lower exposure times
- Stackable after drying prior to exposure
- Increased adhesion to stiffener/coverlay materials

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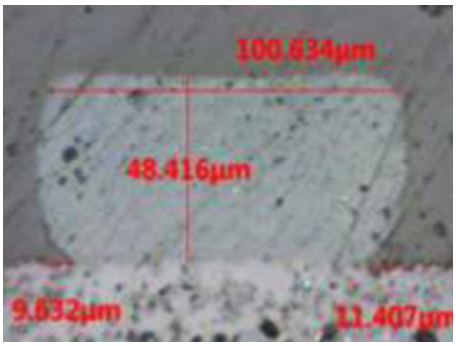
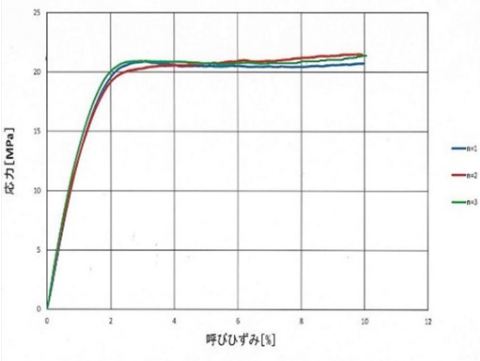
Performance Properties:

- Extremely high heat resistance to multiple soldering operations, capable of lead-free soldering/hot bar processing up to 340°C
- High 365nm spectra absorption along with 405nm
- Low exposure energy with minimal undercut
- Resolution capability below 3 mils for ultra-fine pitch dams
- Tack-Free Surface for stackable processing
- Excellent black cosmetic appearance with minimal imaging circuit diagrams
- Can use either standard exposure equipment or UV/LED/multiple laser direct imaging systems
- High flexibility before and after primary bake along with high elasticity
- Meets or exceeds IPC SM 840E, Bellcore TR-NWT-000078, and MIL P55110D specifications
- UL 94 V-0/VTM-0 certified product/File #E83246, meets minimum 94 VTM-0 specifications with specific parameters (PI grade, PI thickness, and solder mask thickness) under UL certifications. (see UL certification note)
- Complies with NASA outgassing specification (MICRO VCM TEST/ASTM E-595-93)
- Halogen, Sb, Be, and Phthalate Free - RoHS compliant
- Superior resistance to all plated surface finishing processes including ENIG, ENEPIG, Tin/Lead, Nickel, and Tin
- Resistant to downstream processing chemicals including no clean fluxes, cleaners, solvents, etc



Fine solder dam features
exhibit minimized undercut


Superior Resistance to Plated Surface
Finishes and downstream processing chemicals



High Flexibility and Elasticity


High heat resistance
340°C for 5 sec dipping x 3 times

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